ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

IPC-2223A

Sectional Design Standard for Flexible Printed Boards

Developed by the Flexible Circuits Design Subcommittee (D-11) of the Flexible Circuits Committee (D-10) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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Table of Contents

1 SCOPE 1
1.1 Purpose 1
1.2 Classification of Products 1
1.2.1 Board Type 1
1.2.2 Installation Uses 1
1.3 Revision Level Changes 2
2 APPLICABLE DOCUMENTS 2
2.1 IPC 2
3 GENERAL REQUIREMENTS 2
3.1 Design Modeling 2
3.2 Design Layout 2
3.2.1 Mechanical Layout Efficiency (Consider Final Panelization) 3
3.2.2 Fabrication Drawing Recommendations 3
3.3 Schematic 3
3.4 Test Requirement Considerations 3
3.4.1 Environmental 3
3.4.2 Mechanical/Flexural 3
4 MATERIALS 3
4.1 Material Selection 3
4.1.1 Material Options 4
4.2 Dielectric Materials (Including Prepreg and Adhesives) 4
4.2.1 Preimpregnated Bonding Material (Prepreg) 4
4.2.2 Adhesives (Liquid) 4
4.2.3 Flexible Adhesive Bonding Films (Cast Adhesive or Bondply) 4
4.2.4 Conductive Anisotropic Adhesives 5
4.2.5 Coverlayer 5
4.3 Conductive Materials (Surface Finishes) 6
4.3.1 Electrolytic Copper Plating 6
4.3.2 Nickel 7
4.3.3 Tin-Lead Plating 7
4.3.4 Solder Coating 7
4.3.5 Other Metallic Coatings 7
4.3.6 Electronic Component Materials (Buried Resistors and Capacitors) 7
4.3.7 Conductive Coatings for Shielding 7
4.4 Organic Protective Coatings 7
4.4.1 Solder Resist 7
4.4.2 Conformal Coating 7
4.5 Marking and Legend 7
5 MECHANICAL AND PHYSICAL PROPERTIES 8
5.1 Fabrication Requirements 8
5.1.1 Bare Board Fabrication 8
5.1.2 Roll to Roll Fabrication 8
5.2 Product/Board Configuration 8
5.2.1 Circuit Profile (Outline) 8
5.2.2 Rigid Area Considerations 9
5.2.3 Flexible Areas 9
5.2.4 Preforming Bend 12
5.2.5 Differential Lengths 13
5.2.6 Shielding 15
5.2.7 Ground/Power Plane 15
5.2.8 Stiffeners and Heat Sinks 15
5.2.9 Fillets (Strain Relief) 16
5.3 Assembly Requirements 16
5.3.1 Mechanical Considerations 16
5.3.2 Palletized Flexible and Rigid Flex Printed Wiring 16
5.3.3 Nonpalletized Flexible and Rigid Flex Printed Wiring 16
5.3.4 Moisture 16
5.3.5 Infrared Preheats and Reflow 16
5.3.6 Adhesive T_g 16
5.4 Dimensioning 16
5.4.1 Datum Features 17
6 ELECTRICAL PROPERTIES 17
6.1 Electrical Considerations 17
6.2 Impedance and Capacitance Control 17
7 THERMAL MANAGEMENT 17
8 COMPONENT AND ASSEMBLY ISSUES 17
8.1 General Placement Requirements 17
8.2 Standard Surface Mount Requirements 17
8.3 Lands for Surface Mounting 17
8.4 Constraints on Mounting to Flexible Sections 17
8.5 Interfacial Connections 18
8.6 Offset Lands 18
9 HOLES/INTERCONNECTIONS 18
9.1 General Requirements for Lands with Holes 18
9.1.1 Land Requirements 18
9.1.2 Annular Ring Requirements 18
9.1.3 Eyelet or Standoff Land Area Considerations 18

9.1.4 Land Size for Nonplated Component Holes 18
9.1.5 Land Size for Plated-Through Component Holes 18
9.1.6 Thermal Relief in Conductor Planes 18
9.1.7 Surface Mount Components 18
9.1.8 Nonfunctional Lands 18
9.1.9 Land-to-Conductor Transition 19
9.2 Holes 19
9.2.1 Unplated Component Holes 19
9.2.2 Plated Component Holes 19
9.3 Coverlayer Access Openings 19
9.3.1 Coverlayer Access, Unsupported Lands 19
9.3.2 Coverlayer Access, Holes 20
9.3.3 Coverlayer Access Spacing 20
9.3.4 Land Access/Exposed Lands 20

10 CONDUCTORS 21
10.1 Conductor Characteristics 21
10.1.1 Conductor Routing 21
10.1.2 Conductor Edge Spacing 21
10.2 Land Characteristics 21
10.3 Large Conductive Areas 21

11 DOCUMENTATION 21

12 QUALITY ASSURANCE 21

Figures

Figure 1-1 Board Type 1 1
Figure 1-2 Board Type 2 1
Figure 1-3 Board Type 3 1
Figure 1-4 Board Type 4 2
Figure 1-5 Board Type 5 2
Figure 3-1 Three Dimensional Modeling 3
Figure 3-2 Final Panelization 3
Figure 4-1 Flexible Cross-Sectional Construction Examples 4
Figure 4-2 Unbonded Flex Cross-Sectional Construction of Rigid Flex 5
Figure 4-3 Selective Plating 7
Figure 5-1 Circuits Nested on a Panel 8
Figure 5-2 Special Flexible Printed Wiring Features 8
Figure 5-3 Cutout with a Drilled Hole 8
Figure 5-4 Reinforcement Patch for Flex Area 8
Figure 5-5 Slits and Slots 9
Figure 5-6 Reduced Bend Radii 10
Figure 5-7 Conductors in Bend Areas 11
Figure 5-8 Bend/Crease Areas Center Lines 11
Figure 5-9 Neutral Axis Ideal Construction 11
Figure 5-10 Stresses on Layers During Folding 12
Figure 5-11 Fold Back 14
Figure 5-12 Irregular Folds 14
Figure 5-13 Differential Board Lengths 14
Figure 5-14 Differential Board Lengths, Rigid-Flex 14
Figure 5-15 Bookbinder 15
Figure 5-16 Typical Example of Copper Removal for Flexible Shielding 16
Figure 5-17 Adhesive Fillets (Strain Relief) 16
Figure 5-18 Establishing Datums 17
Figure 9-1 Conductor to Land Transitions 18
Figure 9-2 Coverlay Access Openings and Exposed Unsupported Lands 20
Figure 9-3 Coverlay Access Opening for Unsupported Lands 20
Figure 9-4 Coverlay Access Openings and Exposed Supported Lands 21
Figure 10-1 Conductor Routing, Rigid-Flex Transition 21

Tables

Table 4-1 Characteristics of Typical Flexible Dielectrics 6
Table 4-2 Minimum Average Copper Thickness 7
Table 9-1 Minimum Standard Fabrication Allowance for Interconnection Lands 18
Table 9-2 Nonfunctional Land Considerations 19

Sectional Design Standard for Flexible Printed Boards

1 SCOPE

This standard establishes the specific requirements for the design of flexible printed circuit applications and its forms of component mounting and interconnecting structures. The flexible materials used in the structures are comprised of insulating films, reinforced and/or nonreinforced, dielectric in combination with metallic materials. These interconnecting boards may contain single, double, multilayer, or multiple conductive layers and can be comprised wholly of flex or a combination of both flex and rigid.

1.1 Purpose The requirements contained herein are intended to establish specific design details that **shall** be used in conjunction with IPC-2221 and may also be used in conjunction with IPC-2222 for the rigid sections of rigid-flex circuits.

1.2 Classification of Products Classification type and use of products **shall** be in accordance with IPC-2221 and as stated in 1.2.1 and 1.2.2.

1.2.1 Board Type

Type 1 Single-sided flexible printed wiring containing one conductive layer, with or without stiffener (see Figure 1-1).

Type 2 Double-sided flexible printed wiring containing two conductive layers with plated-through holes, with or without stiffeners (see Figure 1-2).

Type 3 Multilayer flexible printed wiring containing three or more conductive layers with plated-through holes, with or without stiffeners (see Figure 1-3).

Type 4 Multilayer rigid and flexible material combinations containing three or more conductive layers with plated-through holes (see Figure 1-4).

Type 5 Flexible or rigid-flex printed wiring containing two or more conductive layers without plated-through holes (see Figure 1-5).

1.2.2 Installation Uses Flexible circuit designs are unique in each application: however, the following are some typical classes of use. It is recommended that the intended use be specified on the fabrication drawing. It may be necessary to define specific tests for design verification on the master drawing. These categories can be used individually or in a combination.

Use A Capable of withstanding flex during installation (flex-to-install) (see 5.2.3.2).

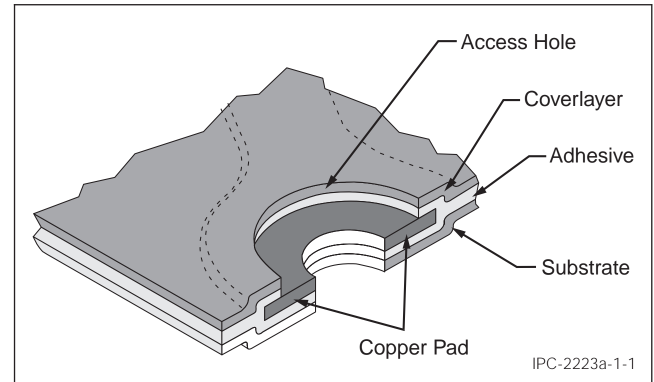

Figure 1-1 Board Type 1

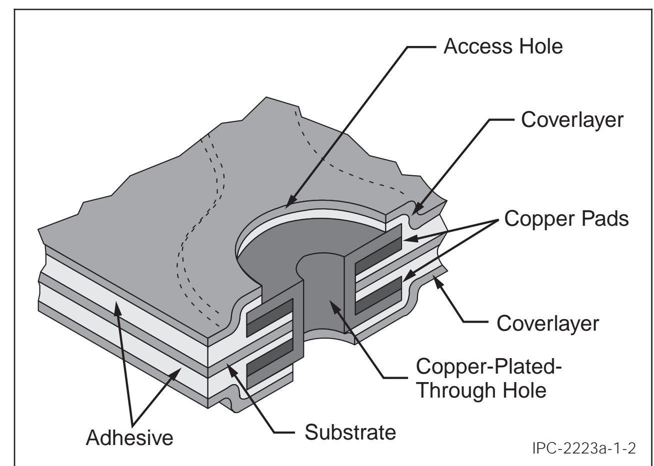

Figure 1-2 Board Type 2

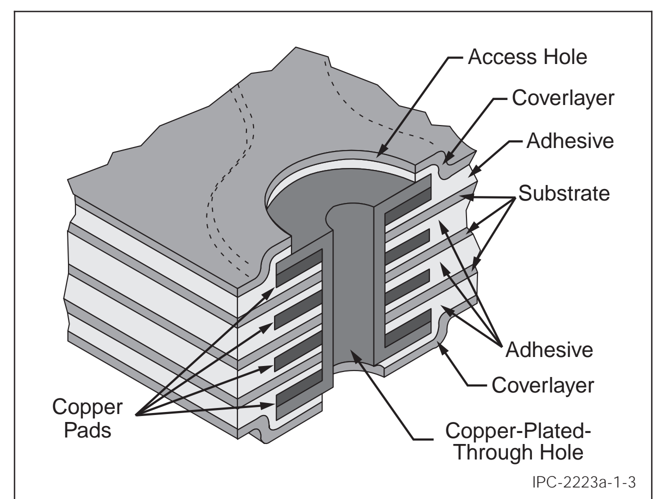

Figure 1-3 Board Type 3

Use B Capable of withstanding continuous flexing for the number of cycles as specified on the master drawing (dynamic flex) (see 5.2.3.2).